

Type number	Package	Package description	Total product weight
74AUP1G07GX4	SOT1269-2	X2SON4	0.36986 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935340115147	5	1	260	30 s	1	240	20 s	3	Shanghai, China; Bangkok, Thailand; Seremban, Malaysia	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.01820	100.00000	4.92065
		subTotal		0.01820	100.00000	4.92065
Component	Additive	Non hazardous	Proprietary	0.00010	5.00000	0.02704
	Filler	Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.00010	5.00000	0.02704
		Silica -amorphous-	7631-86-9	0.00100	50.00000	0.27037
		Epoxy resin system	Proprietary	0.00060	30.00000	0.16222
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.00020	10.00000	0.05407
		subTotal			0.00200	100.00000
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	0.13097	93.54790	35.40990
		Magnesium (Mg)	7439-95-4	0.00020	0.14590	0.05523
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00408	2.91730	1.10426
		Silicon (Si)	7440-21-3	0.00088	0.63210	0.23926
	Pure metal layer	Gold (Au)	7440-57-5	0.00008	0.05830	0.02207
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00352	2.51720	0.95281
		Palladium (Pd)	7440-05-3	0.00025	0.18130	0.06863
subTotal			0.14000	100.00000	37.85216	
Mould Compound	Additive	Misc. Phosphor compounds (generic)	7723-14-0	0.00020	0.10000	0.05516
		Non hazardous	Proprietary	0.00734	3.60000	1.98562
	Filler	Silica fused	60676-86-0	0.17952	88.00000	48.53728
		Carbon black	1333-86-4	0.00041	0.20000	0.11031
	Polymer	Phenolic resin	Proprietary	0.00836	4.10000	2.26140
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.00816	4.00000	2.20624
subTotal			0.20400	100.00000	55.15601	
Wire	Impurity	Non hazardous	Proprietary	0.00000	0.01000	0.00015
	Pure metal	Copper (Cu)	7440-50-8	0.00546	96.49000	1.47693
	Pure metal layer	Gold (Au)	7440-57-5	0.00003	0.50000	0.00765
		Palladium (Pd)	7440-05-3	0.00017	3.00000	0.04592
	subTotal			0.00566	100.00000	1.53065

#### Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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